



Material Content Data Sheet



Sales Product Name		ESD8V0L2B-03L E6327		Issued		25. September 2017		
MA#		MA000251707						
Package		PG-TSLP-3-1		Weight*		0.55 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.16		1648	
	noble metal	gold	7440-57-5	0.004	0.64		6390	
	inorganic material	silicon	7440-21-3	0.043	7.80	8.60	77998	86036
leadframe	non noble metal	nickel	7440-02-0	0.071	12.95	12.95	129511	129511
wire	noble metal	gold	7440-57-5	0.012	2.14	2.14	21407	21407
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.000	0.04		367	
	organic material	carbon black	1333-86-4	0.004	0.74		7350	
	plastics	epoxy resin	-	0.055	9.92		99223	
	inorganic material	silicondioxide	60676-86-0	0.346	62.81	73.51	628045	734985
leadfinish	noble metal	gold	7440-57-5	0.008	1.40	1.40	14020	14020
plating	noble metal	gold	7440-57-5	0.008	1.40	1.40	14041	14041
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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